



LP 5707
DP 5505

Cleaning Processes for Flux and Solder Paste Removal



The following cleaning testing has been conducted at both Interflux and ZESTRON Application Technology Centers. Prior to this recommendation by Interflux, the board cleanliness level had been assessed successfully in accordance to the following standards:

- IPC 610
- J-STD 001
- IPC-TM 650

ZESTRON conducts comprehensive cleaning trials in its European, American and Asian Technical Centers. In collaboration with leading, global equipment manufacturers, ZESTRON's Technical Centers are featured with state-of-the-art cleaning processes such as spray-in-air, ultrasonic and spray-under-immersion. Therefore, ZESTRON's Technical Centers are most suited to perform any cleaning trials. For free of charge cleaning trials, please contact ZESTRON's Application Technology Department.

Flux Removal in an Aqueous Cleaning Process:

BATCH CLEANING PROCESS: SPRAY IN AIR					
VIGON® A 200	Conc.	Cleaning time	Cleaning temperature	Rinsing agent	Drying
LP 5707	30 %	10 min	60° C	DI-water	Circulating air
DP 5505	30 %	10 min	60° C	DI-water	Circulating air

BATCH CLEANING PROCESS: SPRAY IN AIR					
VIGON® A 201	Conc.	Cleaning time	Cleaning temperature	Rinsing agent	Drying
LP 5707	20 %	10 - 12 min	60° C	DI-water	Circulating air
DP 5505	20 %	10 - 12 min	60° C	DI-water	Circulating air

BATCH CLEANING PROCESS: SPRAY IN AIR					
VIGON® N 600	Conc.	Cleaning time	Cleaning temperature	Rinsing agent	Drying
LP 5707	20 %	10 min	50° C	DI-water	Circulating air
DP 5505	20 %	10 - 15 min	60° C	DI-water	Circulating air

BATCH CLEANING PROCESS: SPRAY IN AIR					
VIGON® A 300	Conc.	Cleaning time	Cleaning temperature	Rinsing agent	Drying
LP 5707	33 %	10 - 12 min	60° C	DI-water	Circulating air
DP 5505	33 %	10 - 12 min	60° C	DI-water	Circulating air



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BATCH CLEANING PROCESS: SPRAY IN AIR					
ATRON® AC 207	Conc.	Cleaning time	Cleaning temperature	Rinsing agent	Drying
LP 5707	15 %	10 - 12 min	60°C	DI-water	Circulating air
DP 5505	15 %	10 min	50° C	DI-water	Circulating air

ULTRASONIC CLEANING PROCESS					
VIGON® US	Conc.	Cleaning time	Cleaning temperature	Rinsing agent	Drying
LP 5707	30 %	10 min	60° C	DI-water	Circulating air
DP 5505	30 %	15 min	60° C	DI-water	Circulating air

Batch cleaning processes are renowned for their small footprint and are mostly recommended for high mix / low volume production.

Flux Removal in a Semi-Aqueous Cleaning Process:

ULTRASONIC CLEANING PROCESS					
ZESTRON® FA+	Conc.	Cleaning time	Cleaning temperature	Rinsing agent	Drying
LP 5707	ready to use	10 - 12 min	60° C	DI-water	Circulating air
DP 5505	ready to use	10 - 12 min	60° C	DI-water	Circulating air

Ultrasonic cleaning processes are most effective with hard substrates such as ceramics. The high bath loading capability of ZESTRON® FA+ compared to traditional solvents, ensures an extended bath life and a very cost effective process.

PRODUCT INFORMATION



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